



Material Content Data Sheet



Sales Product Name	IRL40T209			Issued	9. January 2019			
MA#	MA001723486							
Package	PG-HSOF-8-1			Weight*	772.97 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.002	0.91	0.91	9059	9059
leadframe	inorganic material	phosphorus	7723-14-0	0.126	0.02		163	
	non noble metal	iron	7439-89-6	0.421	0.05		544	
	non noble metal	copper	7440-50-8	420.040	54.33	54.40	543410	544117
	non noble metal	aluminium	7429-90-5	14.952	1.93	1.93	19343	19343
wire	non noble metal	aluminium	7429-90-5	14.952	1.93	1.93	19343	19343
encapsulation	organic material	carbon black	1333-86-4	4.760	0.62		6159	
	plastics	epoxy resin	-	52.364	6.77		67744	
	inorganic material	silicondioxide	60676-86-0	260.233	33.67	41.06	336666	410569
leadfinish	non noble metal	tin	7440-31-5	6.479	0.84	0.84	8382	8382
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		2	
	non noble metal	nickel	7440-02-0	0.526	0.07	0.07	680	682
solder	non noble metal	tin	7440-31-5	0.121	0.02		157	
	noble metal	silver	7440-22-4	0.152	0.02		196	
	non noble metal	lead	7439-92-1	5.793	0.75	0.79	7495	7848
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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